

Leading the New Future of Mobile Communications

引领移动通信“芯”未来

Speaker



Dan Li,

Marketing director of
HED

李旦 华大电子市场总监

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Hosted @ **MWC**
GSMA

eSIM: 引领移动通信“芯”未来

eSIM: Leading the New Future of Mobile Communications

华大电子/HED
李旦/Nadeel Lee

华大电子 – 中国安全芯片龙头企业

HED – China's leading Security Chip supplier



SIM芯片累计出货量超180亿颗;

SIM chip shipment > 18 billion



首家超级SIM芯片供应商

累计出货量超1亿颗;

First SWP-SIM chip supplier, Shipment > 100 million



eSIM芯片覆盖消费级/工业级/车规级

累计出货量超过10亿颗;

Consumer/Industrial/Automotive grade
shipment > 1 billion

HED

00085.HK
CEC Group

TOP3

Global SIM/eSIM IC Supplier

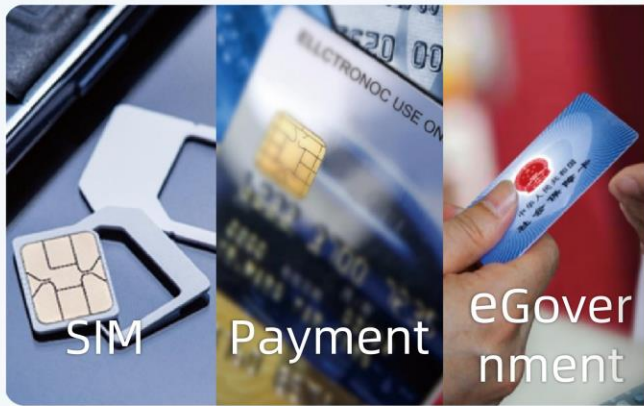
25 Billion

Shipment

2.7 Billion

Revenue in RMB

HED Offering



Smart Card

Mobile Security

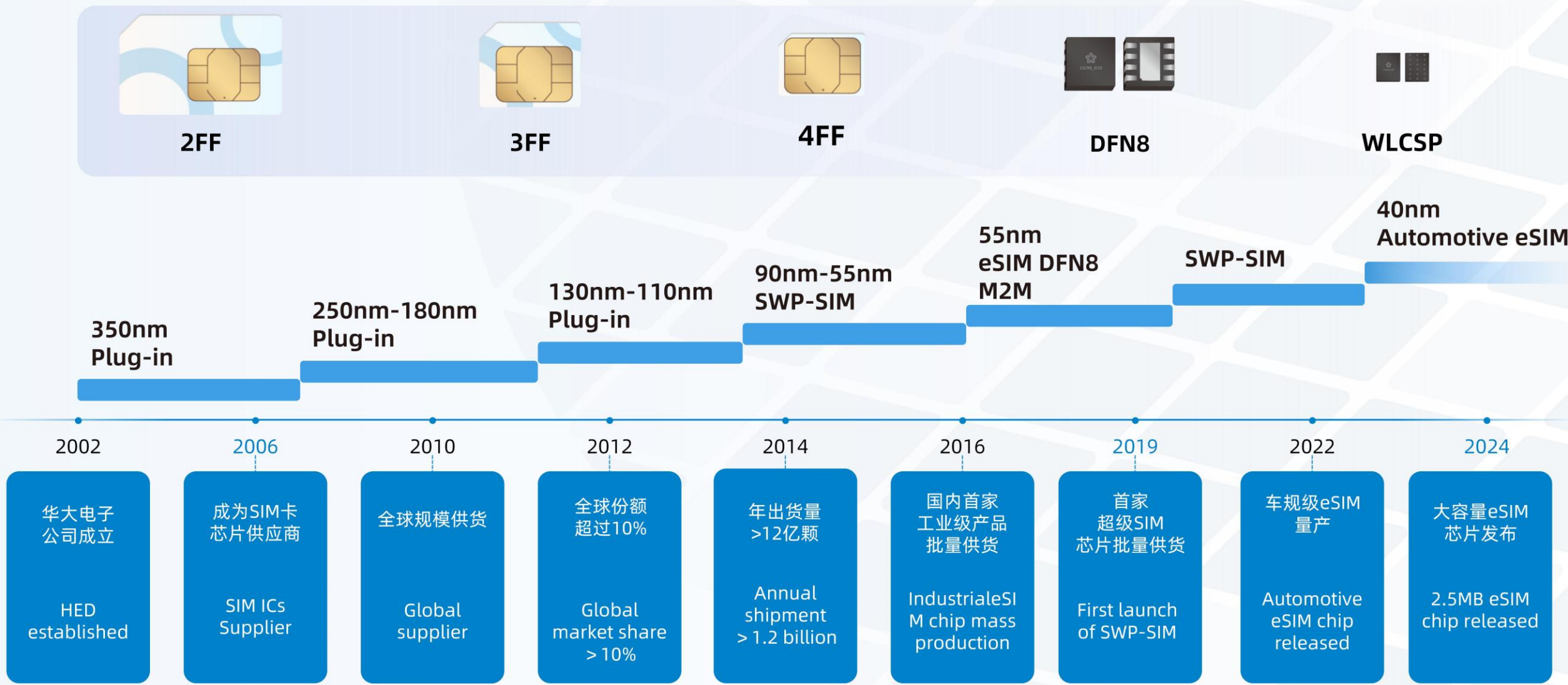


IoT Security

IoV Security



SIM Evolution



HED's eSIM Offering

	Consumer	IoT
HW	eSIM IC for Consumer up to 2.5MB NVM Consumer Grade	eSIM IC for IoT up to 700kB NVM Industrial Grade
OS	Consumer SGP.22 v2.5&v3.1 GSMA compliant	Consumer & IoT SGP.22 v2.2 & SGP.32 v1.1 GSMA compliant
Package	WLCSP	DFN8(MFF2, DFN8 3*3)
Personalisation	Perso on wafer SAS-UP site	Perso on package SAS-UP site
LPA	LPAd reference	LPAd/IPA reference

HED's new eSIM Chip

国内首款“最大容量、工艺最先进”安全芯片

China's first maximum capacity security chip with 40nm eFlash processing

2.5MB eFLASH

15+ profiles

OS Update

High Capacity

CPU 120MHz

ALG performance X 3

High Performance

CC EAL6+

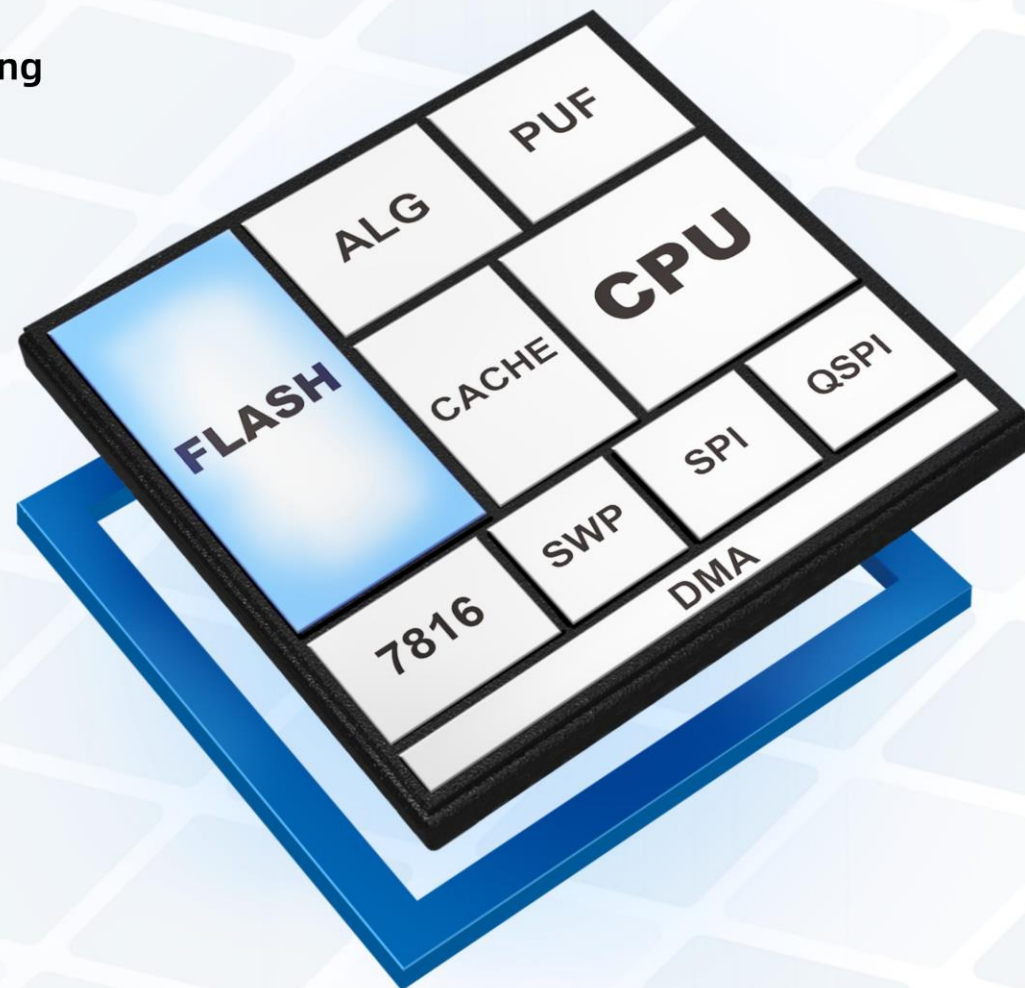
PUF

High Security

WLCSP

Perso on Wafer

Small package



HED's eSIM Solution

HED提供eSIM整体解决方案

HED Provides eSIM total solution



采用最先进的eSIM

安全芯片
Advanced
eSIM chip



支持最新功能特性

多个码号同时激活成为可能
Newest features E.g MEP



全球运营商平台互操作

覆盖全球200+运营商
200+ MNOs interoperability



支持多运营商配置

15+ profile
multiple network
operator profiles



符合**GSMA**最新
RSP技术规范

GSMA compliant OS

符合**GSMA**产品认证

GSMA eSA certified

GSMA™



HED eSIM Advantages

LARGER 更大空间，更多可能

- Larger free user memory
- **15+** SIM profiles
- OS Update
- Multiple SIM profiles(MEP)
- Multiple applications

SMALLER 更小尺寸，更加灵活

- Small WLCSP packaging
- **94%** less space than a physical card

FASTER 更快速度，更强体验

- Profile download speeds up to **5x** faster
- Profile local management speeds up to **6x** faster

eSIM Benefits



For End User:

Easier to switch networks

灵活切换运营商



For OEM:

Improve Reliability

Water&Temperature-Resistant

抵御恶劣环境影响，易于做结构防水

Improve device flexibility

Reduce space for better device design

更大的设备灵活性，减小空间，利于设备设计



广泛普及与应用
Widely applied



设备设计与创新
Device innovation



物联网连接简化
Simplified IoT connectivity

Imagine the Future



Thank you

Welcome to Hall N1

展厅位置
N1·E94

